

Socket No.: 004066 USA D01/Consilium/Consilium

PATENT/OFFICIAL

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Application of

John F. ARACKAPARAMBIL et al.

Serial No. 10/084,092

Filed: February 28, 2002

For: COMPUTER INTEGRATED MANUFACTURING TECHNIQUES

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: Group Art Unit: 2121
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: Examiner:

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Technology Center 2100

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Honorable Commissioner for Patents
Washington, D.C. 20231

Sir:

In accordance with the provisions of 37 C.F.R. 1.56, 1.97 and 1.98, the attention of the Patent and Trademark Office is hereby directed to the documents listed on the attached form PTO-1449. It is respectfully requested that the documents be expressly considered during the prosecution of this application, and that the documents be made of record therein and appear among the "References Cited" on any patent to issue therefrom. Copies of the references listed on pages 1 and 2 of Form PTO-1449 are submitted herewith.

This Information Disclosure Statement is being filed within three months of the U.S. filing date OR before the mailing date of a first Office Action on the merits. No certification or fee is required.

This submission does not constitute a representation that a search has been made or that no better art exists and does not constitute an admission or representation that any of the listed documents is material or constitutes prior art. If it should be determined that any of the listed documents does not constitute prior art under the United States law, Applicants reserve the right

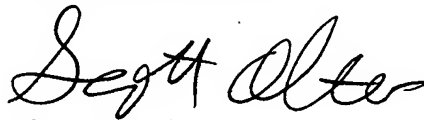
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to present to the Office the relevant facts and law regarding the appropriate status of such document.

No certification or fee is believed to be required. However, the Commissioner is hereby authorized to charge any additional fees should any be required for this submission, or credit any overpayment to deposit account no. 08-0219.

Respectfully submitted,

HALE AND DORR LLP

A handwritten signature in black ink, appearing to read "Scott M. Alter", written in a cursive style.

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INFORMATION DISCLOSURE
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(PTO-1449)



ATTY. DOCKET NO.
004066 USA
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EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
	3,205,485	09/07/65	Noltingk			10/21/60
	3,229,198	01/11/66	Libby			09/28/62
	4,000,458	12/28/76	Miller et al.			08/21/75
	4,302,721	11/24/81	Urbanek et al.			05/15/79
	4,750,141	06/07/88	Judell et al.			11/26/85
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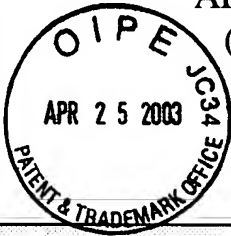
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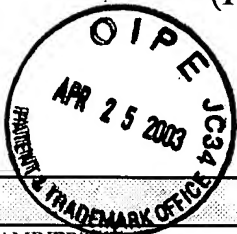
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EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						Yes	No
	61-66104	04/04/86	Japan			X	
	3-202710	09/04/91	Japan			X	
	8-23166	01/23/96	Japan			X	
	9-246547	09/19/97	Japan			X	
	WO 98/05066	02/05/98	WIPO			X	
	10-34522	02/10/98	Japan			X	
	0 869 652	10/07/98	Europe			X	
	WO 99/09371	02/25/99	WIPO			X	
	0 910 123	04/21/99	Europe			X	
	0 932 194	07/28/99	Europe			X	
	WO 00/00874	01/06/00	WIPO			X	
	2000-183001	06/30/00	Japan			X	


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EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						Yes	No
	1 071 128	01/24/01	Europe			X	
	WO 01/18623	03/15/01	WIPO			X	
	WO 01/25865	04/12/01	WIPO			X	
	434103	05/16/01	Taiwan			X	
	436383	05/28/01	Taiwan			X	
	455938	09/21/01	Taiwan			X	
	455976	09/21/01	Taiwan			X	
	2001-284299	10/12/01	Japan			X	
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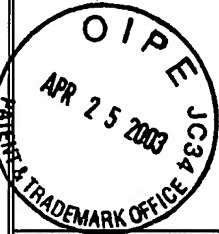
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	<p>APPLICANT John F. ARACKAPARAMBIL et al.</p>	
	<p>FILING DATE February 28, 2002</p>	<p>GROUP 2121</p>
<p style="text-align: center;">OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)</p>		
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<p>OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)</p>		
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<p style="text-align: center;">INFORMATION DISCLOSURE CITATION IN AN APPLICATION (PTO-1449)</p> 	<p>ATTY. DOCKET NO. 004066 USA D01/Consilium/Consilium</p>	<p>SERIAL NO. 10/084,092</p> <p style="text-align: center;">RECEIVED</p> <p style="text-align: center;">APR 28 2003</p>
	<p>APPLICANT John F. ARACKAPARAMBIL eTechnology Center 2100</p>	
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